

INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

Docket Number (Optional)

BU9-98-110

Application Number

09/298,786

Applicant(s)

Armbrust et al

Filing Date

04/23/99

Group Art Unit

2813

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	IF APPROPRIATE
DHLC		5,447,887	09/05/95	Filipiak et al.			
DHLC		5,633,047	05/1997	Brady et al.	427	437	
DHLC		4,505,029	03/1985	Owyang et al.	427	89	
DHLC		5,833,758	04/1997	Linn et al.	134	1.2	
DHLC		5,503,704	04/1996	Bower et al.	427	399	
DHLC		6,046,101	04/2000	Dass et al.	438	791	
DHLC		5,844,317	12/1998	Bertolet et al.	257	773	

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

DHLC		IBM Technical Disclosure, Cronin et al., "Copper/Polyimide Structure with Selective Cu3Si/SiO2 Etch Stop," Vol. 37, No. 06A June 1994, p.53.

EXAMINER

Donghee Kang

DATE CONSIDERED

12-21-00

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.